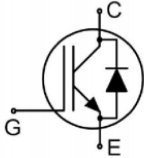


●Features

- Low Gate Charge
- Low Power Loss & High Efficiency
- Guard Ring & Environmental Protection
- High Temperature Application
- Green Molding Compound

●Application

- DC-DC Inverters
- UPS
- Industrial Heating

	$V_{CES}: 650V$ $I_C: 30A$ $V_{CE(SAT)}: 1.74V$
	■ RoHS COMPLIANT TO-247

●Ordering Information:

Part Number	LHG30T65T2HD
Package	TO-247
Basic Ordering Unit (pcs)	330
Normal Package Material Ordering Code	LHG30T65T2HD-TO247-TU
Halogen Free Ordering Code	LHG30T65T2HD-TO247-TU-HF

●Absolute Maximum Ratings (Ta=25℃)

Symbol	Parameter	Rating	Unit
Common Ratings (Ta=25℃ Unless Otherwise Noted)			
V _{CES}	Collector- Emitter Voltage (MIN.)	650	V
V _{GES}	Gate-Emitter Voltage	±20	
I _C	Continuous Collector Current	T _C = 25℃	A
		T _C = 100℃	
I _{CM}	Collector Current Continuous (Note 1.)	120.0	A
I _F	Diode Continuous Forward(T _C =100℃)	30.0	A
P _D	Maximum Power Dissipation (T _C =25℃)	150	W
T _J	Maximum Junction Temperature	-50 to 150	℃
T _{STG}	Storage Temperature Range	-50 to 150	℃
T _L	Maximum Lead Temperature for Soldering Purposes	275	℃

Notes : ¹⁾ Collector current limited by maximum junction temperature.

● Thermal Resistance

Symbol	Parameter	Values		Unit
		Typ.	Max.	
R _{thJC}	Thermal Resistance, Junction - Case	-	0.83	℃/W
R _{thJA}	Thermal Resistance, Junction - Ambient	-	62.5	℃/W

● Electrical Characteristics (T_J=25℃ Unless Otherwise Noted)

Symbol	Parameter	Test Condition	Values			Unit
			Min.	Typ.	Max.	
Off Characteristics						
BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GS} =0V, I _C =250uA	650	-	-	V
I _{CES}	Zero Gate Voltage Drain Current	V _{CE} = 600V, V _{GE} = 0V, T _C =25°C	-	-	1.0	mA
I _{GESF}	Gate-body Leakage Current (Forward)	V _{CE} =0V,V _{GE} =20V	-	-	250	nA
I _{GESR}	Gate-body Leakage Current (Reverse)	V _{CE} =0V,V _{GE} =-20V	-	-	-250	nA
ΔBV _{CES} /ΔT _J	Breakdown Voltage Temperature Coefficient.	I _C =1mA, Reference to 25°C	-	0.6	-	V/°C

• Electrical Characteristics ($T_J=25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Condition	Values			Unit
			Min.	Typ.	Max.	
On Characteristics						
V _{GE(th)}	Gate Threshold Voltage	V _{CE} = V _{GE} , I _C =250uA	3.5	5.0	7.0	V
V _{CE(SAT)}	Collector- Emitter Saturation Voltage	V _{GE} =15V , I _C =20A T _C = 25°C	-	1.74	2.4	V

• Electrical Characteristics ($T_J=25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Condition	Values			Unit
			Min.	Typ.	Max.	
Switching Characteristics						
C _{ies}	Input Capacitance	V _{CE} =30V, V _{GE} =0V, Frequency=1.0MHz	-	4128	-	pF
C _{oes}	Output Capacitance		-	109	-	
C _{res}	Reverse Transfer Capacitance		-	63	-	
t _{d(ON)}	Turn-on Delay Time	V _{CE} = 400V, I _C = 30A, R _G = 10Ω V _{GE} = 15V T _C =25°C	-	64	-	nS
t _r	Turn-on Rise Time		-	46	-	
t _{d(OFF)}	Turn-off Delay Time		-	185	-	
t _f	Turn-off Fall Time		-	40	-	
E _{on}	Turn-on Energy		-	1.21	-	mJ
E _{off}	Turn-off Energy	-	0.5	-		
E _{total}	Total Switching Energy	-	1.71	-		
Q _g	Total Gate Charge	V _{CE} =400V, V _{GE} =15V, I _C =30A	-	163	-	nC
Q _{ge}	Gate to Emitter Charge		-	37	-	
Q _{gc}	Gate to Collector Charge		-	72	-	
Anti-Parallel Diode Characteristics and Maximum Ratings						
V _F	Emitter-Collector Diode Forward Voltage	V _{GS} =0V, I _s =20A	-	2.0	2.6	V
t _{rr}	Reverse Recovery Time	I _S =20A, V _{GE} =0V, V _R =400V di _F /dt=100A/ s (Note 4)	-	40	-	nS
Q _{rr}	Reverse Recovery Charge		-	180	-	nC
I _{RRM}	Diode Reverse Recovery Current		-	6	-	A

Note 1 : Pulse width limited by maximum junction temperature.

Note 2 : Allowed number of short circuits: < 1000 Time between short circuit: >1s.

Note 3 : Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$.

Note 4 : Essentially independent of operating temperature.

● **Electrical Characteristic Curves**

Fig. 1 Typical Output Characteristics

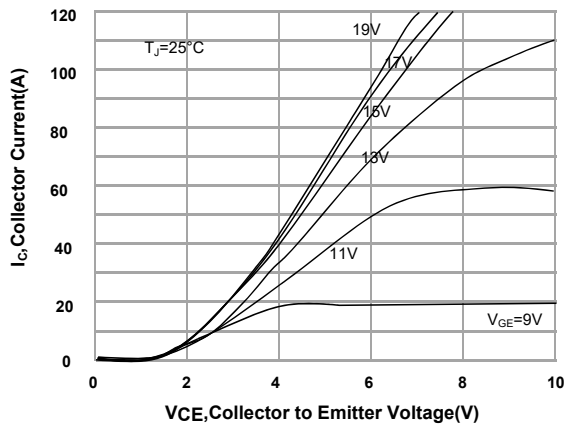


Fig. 2 Typical Output Characteristic

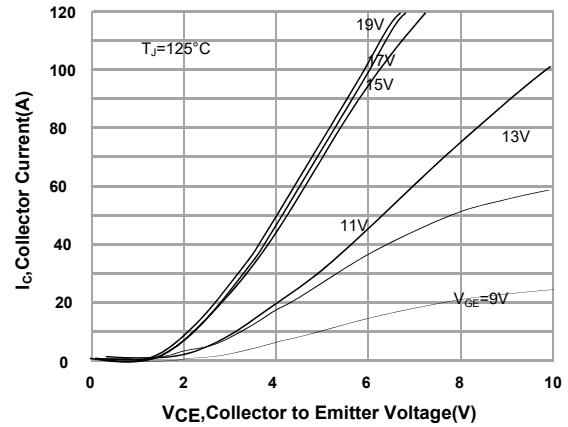


Fig. 3 $V_{CE(SAT)}$ vs. I_C Characteristics

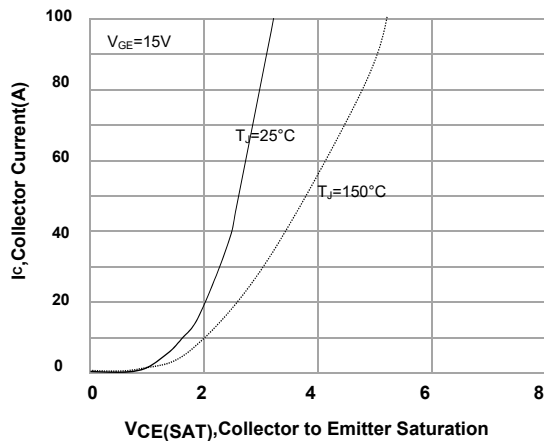


Fig. 4 $V_{CE(SAT)}$ vs. T_C

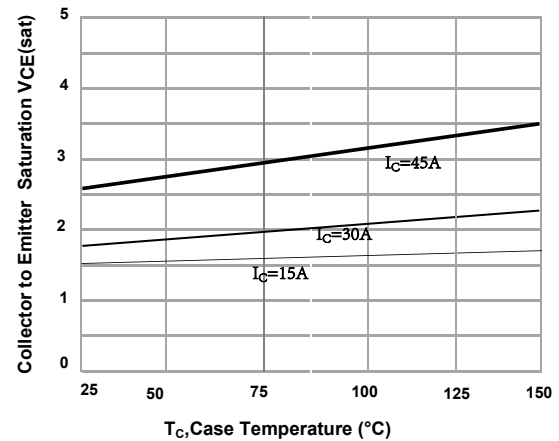


Fig. 5 Capacitance Characteristics

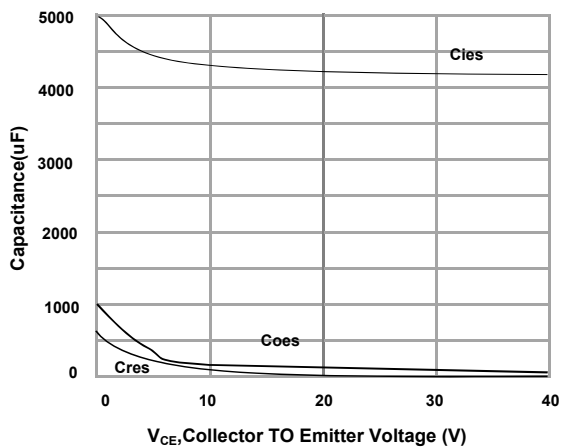
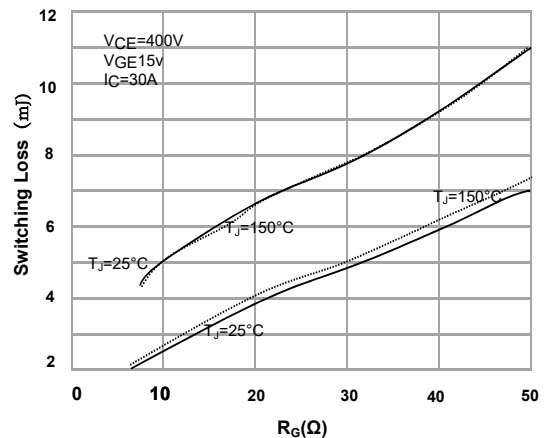
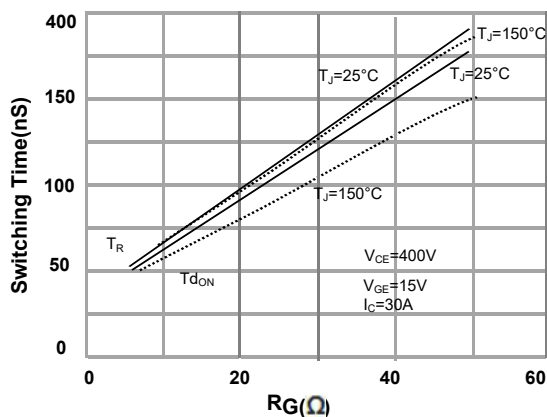
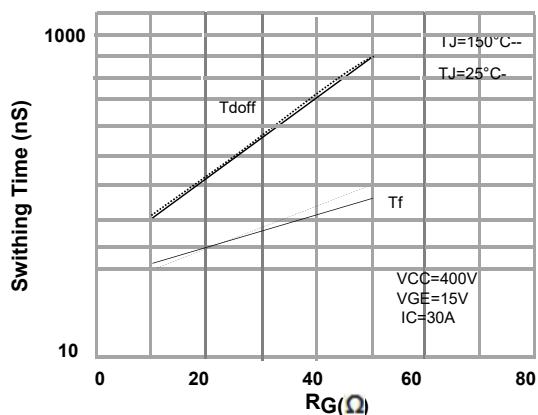
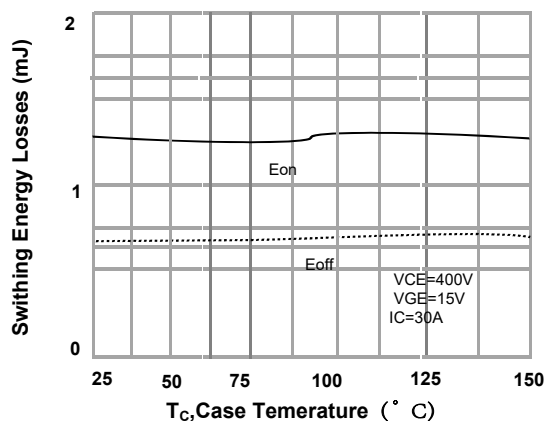
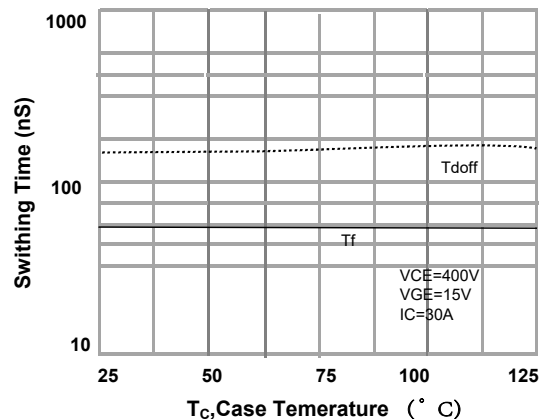
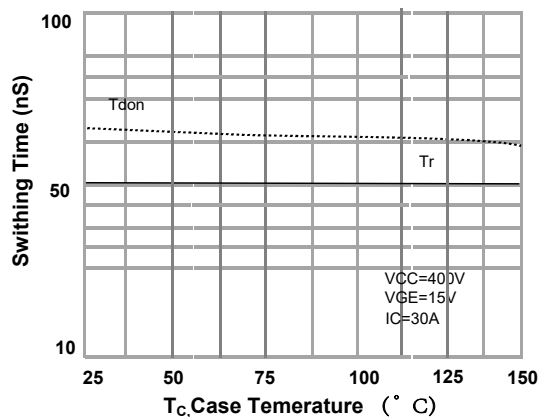
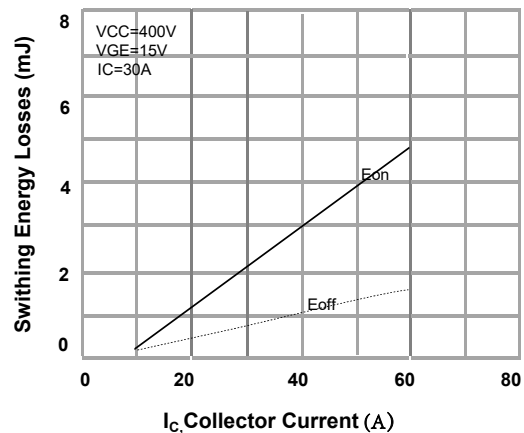


Fig. 6 Switching Energy Loss Characteristics



• Electrical Characteristic Curves

Fig. 7 R_g vs. Switching Time

Fig. 8 R_g vs. Switching Time

Fig. 9 T_C vs. Switching Time

Fig. 10 T_C vs. Switching Time

Fig. 11 T_C vs. Switching Loss

Fig. 12 I_C vs. Switching Loss


● Electrical Characteristic Curves

Fig. 13 I_C vs. Switching Time

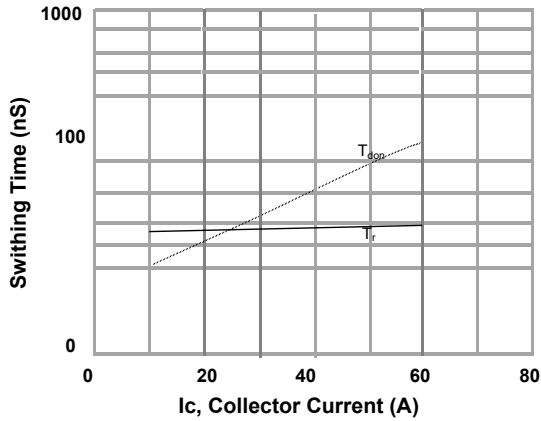


Fig. 14 I_C vs. Switching Time

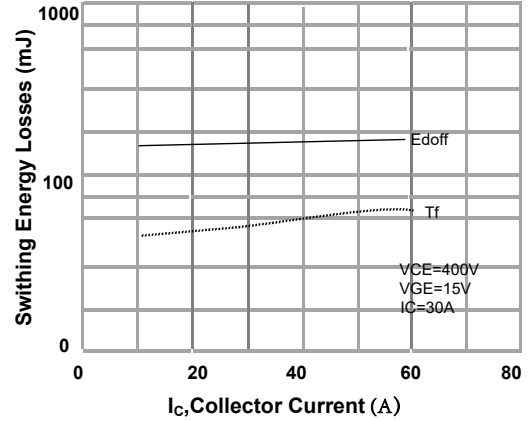


Fig. 14 Forward Safe Operating Area

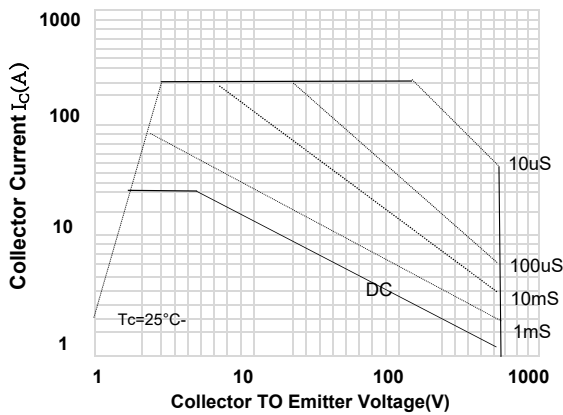


Fig. 15 T_C vs. I_C Current (A)

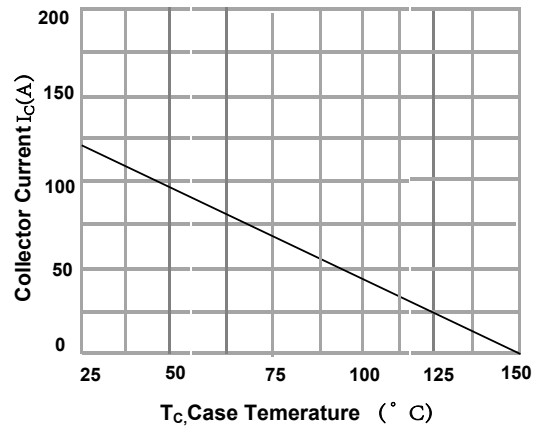
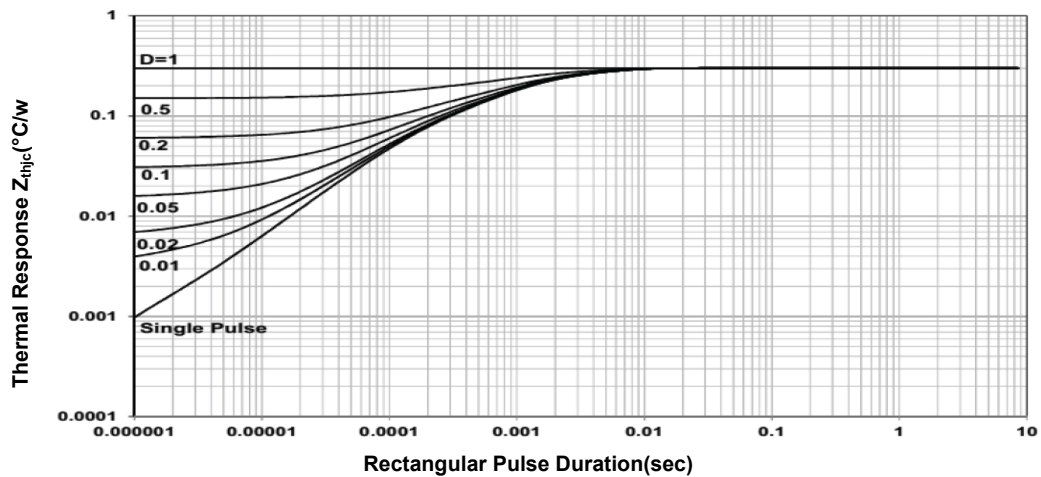


Fig. 19 Transient Thermal Impedance for IGBT



● **Dimensions (TO-247)**

UNIT:mm

SYMBOL	min	max	SYMBOL	min	max
A	15.60	16.00	G2	1.95	2.25
B	20.80	21.20	N	5.25	5.65
C	4.85	5.15	L1	4.00	4.30
D	1.85	2.15	L	19.60	20.40
E	1.00	1.40	I	2.30	2.50
F	0.50	0.70	ΦP	3.30	3.70
G1	3.00	3.30			

